AK

Notice of Allowability	Application No.	Applicant(s)	
	10/718,848	ONO, YOSHIHIRO	
	Examiner	Art Unit	
	Christian Wilson	2891	
The MAILING DATE of this communication apperaisable of the communication apperaisable of the communication apperaisable of the Communication apperaisable of the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this app or other appropriate communication GHTS. This application is subject to	olication. If not includ will be mailed in due	ed course. THIS
1. This communication is responsive to			
2. The allowed claim(s) is/are 1-17.			
3. \boxtimes The drawings filed on <u>21 November 2003</u> are accepted by	the Examiner.		
 4. Acknowledgment is made of a claim for foreign priority una) All b) Some* c) None of the: 1. Certified copies of the priority documents have 2. Certified copies of the priority documents have 3. Copies of the certified copies of the priority documents have International Bureau (PCT Rule 17.2(a)). * Certified copies not received: Applicant has THREE MONTHS FROM THE "MAILING DATE" noted below. Failure to timely comply will result in ABANDONM THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. 5. A SUBSTITUTE OATH OR DECLARATION must be subm INFORMAL PATENT APPLICATION (PTO-152) which give 6. CORRECTED DRAWINGS (as "replacement sheets") must (a) including changes required by the Notice of Draftspers 1) hereto or 2) to Paper No./Mail Date (b) including changes required by the attached Examiner's Paper No./Mail Date Identifying Indicia such as the application number (see 37 CFR 1 each sheet. Replacement sheet(s) should be labeled as such in time. 7. DEPOSIT OF and/or INFORMATION about the deposit attached Examiner's comment regarding REQUIREMENT 	e been received. e been received in Application No cuments have been received in this in of this communication to file a reply IENT of this application. itted. Note the attached EXAMINER es reason(s) why the oath or declarate the submitted. Son's Patent Drawing Review (PTO- as Amendment / Comment or in the Comment or in the Comment of BIOLOGICAL MATERIAL In sit of BIOLOGICAL MATERIAL In	national stage application of the front (not the d). nust be submitted.	quirements NOTICE OF
 Attachment(s) 1. Notice of References Cited (PTO-892) 2. Notice of Draftperson's Patent Drawing Review (PTO-948) 3. Information Disclosure Statements (PTO-1449 or PTO/SB/O Paper No./Mail Date 11212003, 03042005 4. Examiner's Comment Regarding Requirement for Deposit of Biological Material 	5. ☐ Notice of Informal P 6. ☐ Interview Summary Paper No./Mail Dat 7. ☐ Examiner's Amendr 8. ☑ Examiner's Stateme 9. ☑ Other <u>search histor</u>	(PTO-413), te nent/Comment ent of Reasons for Alle	owance

Application/Control Number: 10/718,848 Page 2

Art Unit: 2891

DETAILED ACTION

1. Claims 1 - 17 are allowed.

2. The following is an examiner's statement of reasons for allowance: applicant discloses a novel method of manufacturing a chip-size package where, in the context of the entire claim, a plurality of sprout-shaped metal bumps are formed on electrode pads, then a resin-sealing layer is formed on the surface of the bumps so that the tip of the bumps are projected from the resin, and forming a plurality of wiring patterns on the resin-sealing layer which are electrically connected to the tips of the bumps.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

- 3. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. The cited prior art teaches methods of forming chip-sized packages. Specifically, Tamaki *et al.* (US 6,157,080), Ohuchi (US 2003/0183947), and Onishi (US 6,590,293) teach sprout-shaped metal bumps. Test *et al.* (US 6,268,662) and Kimura (US 6,218,728) teach methods of forming metal bumps by forming a wire bond on an electrode pad and then coating with a sealing resin. Sawai *et al.* (US 6,046,071), Ma *et al.* (US 6,586,836), and Wakabayashi *et al.* (US 6,603,191) teach methods of forming and dicing chip-sized packages.
- 4. A copy of the EAST search history is enclosed.

5. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Christian Wilson whose telephone number is (571) 272-1886. The examiner can normally be reached on weekdays, 7:30 AM to 4 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bill Baumeister can be reached on (571) 272-1722. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

> Christian Wilson, Ph.D. **Primary Examiner**

Page 3

Art Unit 2891

CDW